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Innovations in Optics, Inc. Acquires New Automatic Die Bonder to Keep Up with Rapid Growth

Woburn, MA, August 19, 2019— In our continued strategic pursuit of excellence and improvement, Innovations in Optics, Inc. has purchased a new F&S BONDTEC Model 5830 automatic wire bonder to produce Chip-on-Board die arrays used in the company's high-power UV LED light sources. This new addition will not only expand capacity, but also enhance capabilities. The machine will increase efficiency and overall throughput times. The automatic wire bonder brings value added throughout the entire manufacturing process for the company and reinforces our dedication to quality.

The BONDTEC 5830 can handle bond wire diameters to 3 mils (75 μm), a critical feature for the high current density operation applicable to all LED arrays within products manufactured by Innovations in Optics. Key features of exchangeable bond heads and the ability to store an unlimited number of complex bond programs perfectly support the variety and intricacy of die arrays unique to Innovations in Optics.



About Innovations in Optics, Inc.

Founded in 1993 and located near Boston, Innovations in Optics, Inc. offers high power LED light sources for science and industry that provide maximum photon delivery, illumination uniformity, and stable optical power. Products offer system-level advantages over lasers and arc lamps in OEM equipment for many applications. Available LED wavelengths range from the UV through the near-infrared, including broadband white and multiband options. System accessories include thermal management devices, wire harnesses and driver/controllers. UV LED products support photomask exposure, direct image writing, 3D printing and photocuring. LumiBright™ is a trademark of Innovations in Optics, Inc.